

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 11-260871

(43)Date of publication of application : 24.09.1999

(51)Int.Cl.

H01L 21/66

G01R 1/06

G01R 31/28

(21)Application number : 10-082645

(71)Applicant : TOKYO ELECTRON LTD

(22)Date of filing : 14.03.1998

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(54) PROBE DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a probe device with superior frequency characteristic in which a pin load on a probe card can be reduced, the flatness of the probe card can be maintained, and a thermal effects can be prevented moreover even at high temperature inspection.

SOLUTION: In this probe device, lower contact electrodes 13A of a performance board 13 are arranged to be gathered at the central part, and a spacer 16 having through-holes corresponding to the lower contact electrodes 13A is mounted on the performance board 13. Also an interval δ is interposed between a probe card 12 and the spacer 16, and a pogo pin 18 elastically brought into contact with each bump 12A and the lower contact electrode 13A corresponding to them is mounted on the through-hole of the spacer 16.

